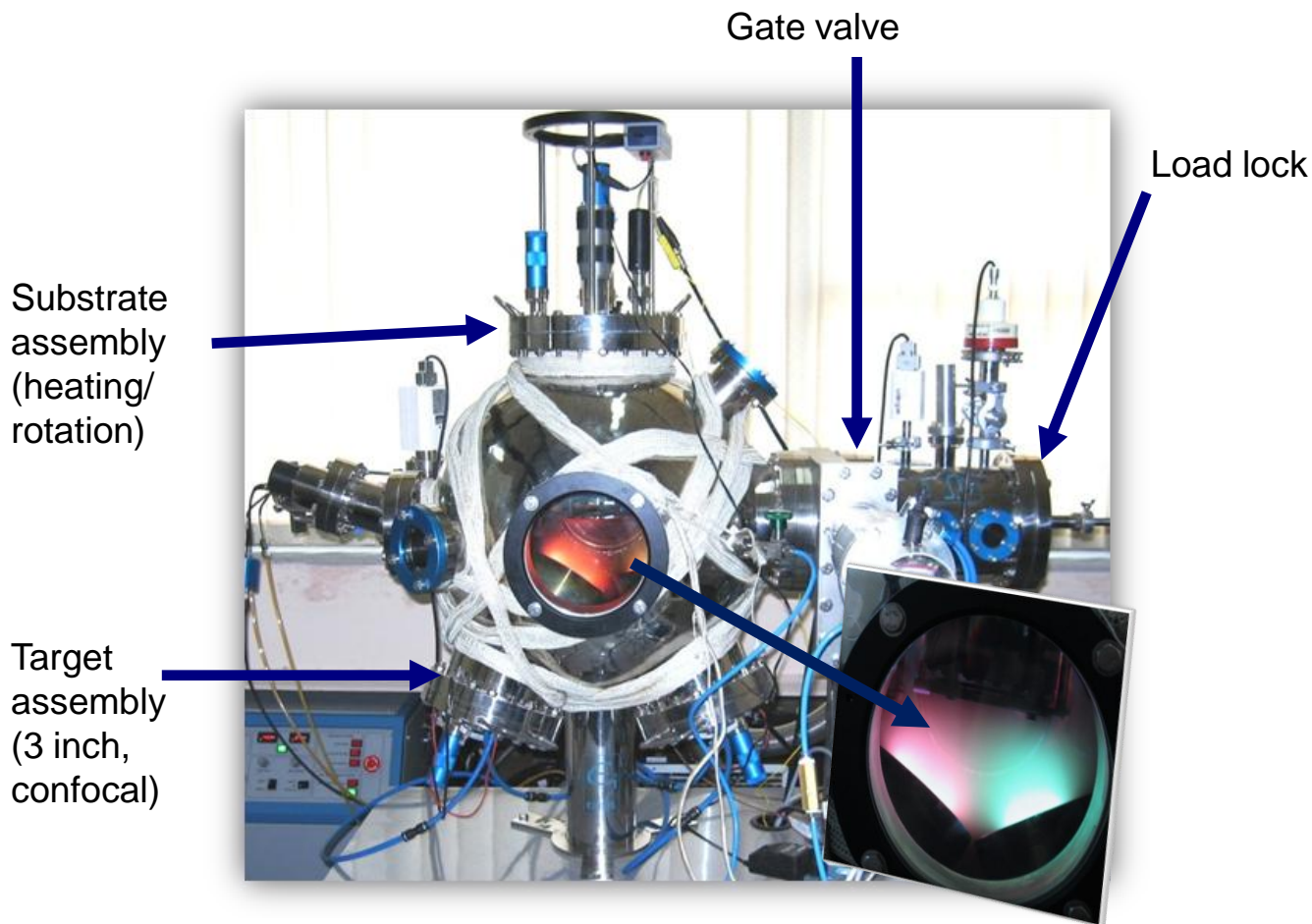


Thin film and multilayer sample preparation

DC/RF magnetron sputter deposition system

The 3-gun sputter up system has been designed to deposit large area thin films and multilayers of various materials (metals, semiconductors, oxides, dielectrics) which can be deposited independently or in combinations of up to three at a time.



Features:

- 3 inch target assemblies powered by D.C. (2) and R.F. (1)
- Variation of target-substrate distance and target tilt
- Load-lock system minimizes contamination
- Ultimate vacuum of $\sim 2 \times 10^{-7}$ mbar
- Substrate rotation and heating (400 °C)
- Reactive gas inlet control.

Advantages:

- Highly reproducible deposition over large area
- Good control over uniformity, thickness and composition.
- Enables formation of co-sputtered alloys for technological applications